

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 08/25/2022

Details for "TP561080DRCR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TP561080DRCR	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DRC   10	3.00X3.00X0.90	24.8

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Copper and Its Alloys	Copper	7440-50-8	0.135815	99.997791	999978	0.547149	5471
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000736	7	0.000004	0
Precious Metals	Silver	7440-22-4	0.000002	0.001473	15	0.000008	0
Sub-Total			0.135818	100	1000000	0.547161	5472
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Silica	7631-86-9	0.008368	2.000076	20001	0.033712	337
Precious Metals	Silver	7440-22-4	0.288685	69.00001	690000	1.163006	11630
Thermoplastics	Epoxy	85954-11-6	0.121331	28.999914	289999	0.488798	4888
Sub-Total			0.418384	100	1000000	1.685515	16855
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	11.18349	99.25	992500	45.054169	450542
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.029297	0.260002	2600	0.118027	1180
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.02817	0.25	2500	0.113487	1135
Zinc and Its Alloys	Zinc	7440-66-6	0.027043	0.239998	2400	0.108946	1089
Sub-Total			11.268	100	1000000	45.394629	453946
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.193094	95.120197	951202	0.777905	7779
Precious Metals	Gold	7440-57-5	0.001583	0.779803	7798	0.006377	64
Precious Metals	Palladium	7440-05-3	0.008323	4.1	41000	0.03353	335
Sub-Total			0.203	100	1000000	0.817812	8178
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	10.343558	90.499999	905000	41.670392	416704
Other Plastics and Rubber	Carbon Black	1333-86-4	0.057147	0.500002	5000	0.230224	2302
Thermoplastics	Epoxy	85954-11-6	1.028641	8.999999	90000	4.144016	41440
Sub-Total			11.429346	100	1000000	46.044632	460446
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	1.367772	100	1000000	5.51025	55103
Sub-Total			1.367772	100	1000000	5.51025	55103
<b>Total</b>			24.82232			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology.

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former IIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality

For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)

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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.